

ES52C1B10N-10.000M

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REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 1, 2017)


[Click badges to download compliance docs](#)

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ITEM DESCRIPTION

Temperature Compensated Quartz Crystal Clock Oscillators TCXO TC(VC)XO Clipped Sinewave 3.3Vdc 10 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 10.000MHz ± 1.0 ppm Maximum 0°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	10.000MHz
Frequency Tolerance	± 1.0 ppm Maximum (at 25°C $\pm 2^\circ\text{C}$, Vdd=3.3Vdc)
Frequency Stability	± 1.0 ppm Maximum (Inclusive of Operating Temperature Range, at Vdd = 3.3Vdc)
Frequency Stability vs. Supply Voltage	± 0.2 ppm Maximum (Vdd $\pm 5\%$)
Frequency Stability vs. Load	± 0.2 ppm Maximum ($\pm 1\text{k}\Omega$ / $\pm 1\text{pF}$)
Frequency Stability vs. Aging	± 1 ppm/Year Maximum (at 25°C)
Operating Temperature Range	0°C to +70°C
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	1.5mA Maximum
Output Voltage	0.8Vp-p Clipped Sinewave Minimum
Load Drive Capability	10kOhms//10pF
Output Logic Type	Clipped Sinewave
Control Voltage	None (No Connect on Pin 1)
Phase Noise	-80dBc/Hz at 10Hz offset, -115dBc/Hz at 100Hz offset, -135dBc/Hz at 1kHz offset, -148dBc/Hz at 10kHz offset, -148dBc/Hz at 100kHz offset (All Values are Typical)
Start Up Time	5mSec Maximum
Storage Temperature Range	-55°C to +125°C

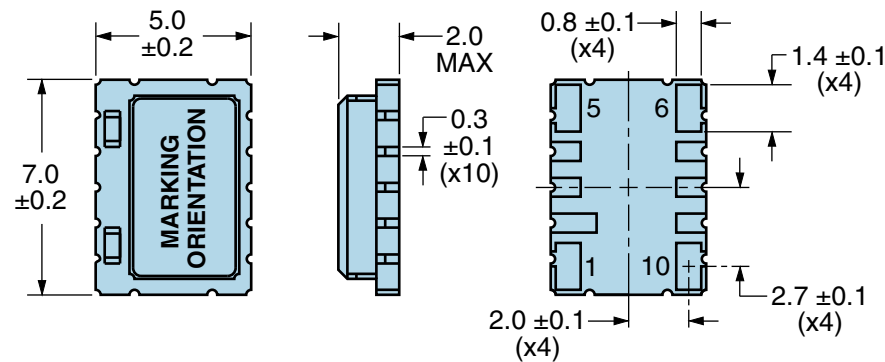
ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

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MECHANICAL DIMENSIONS (all dimensions in millimeters)

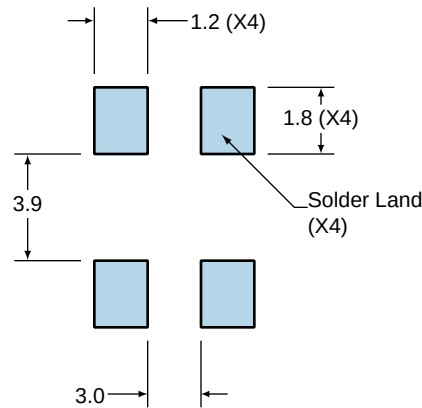


PIN	CONNECTION
1	No Connect
2	Do Not Connect
3	Do Not Connect
4	Do Not Connect
5	Case/Ground
6	Output
7	Do Not Connect
8	Do Not Connect
9	Do Not Connect
10	Supply Voltage

LINE	MARKING
1	E10.000 E=Ecliptek
2	XXXXX XXXXX=Ecliptek Manufacturing Identifier

Suggested Solder Pad Layout

All Dimensions in Millimeters

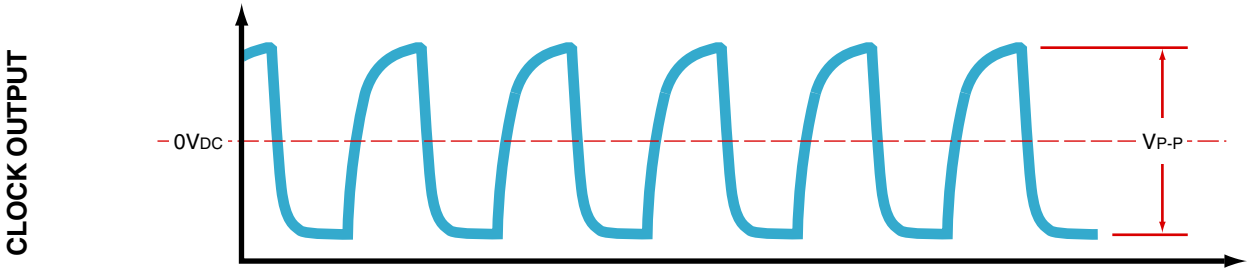


All Tolerances are ±0.1

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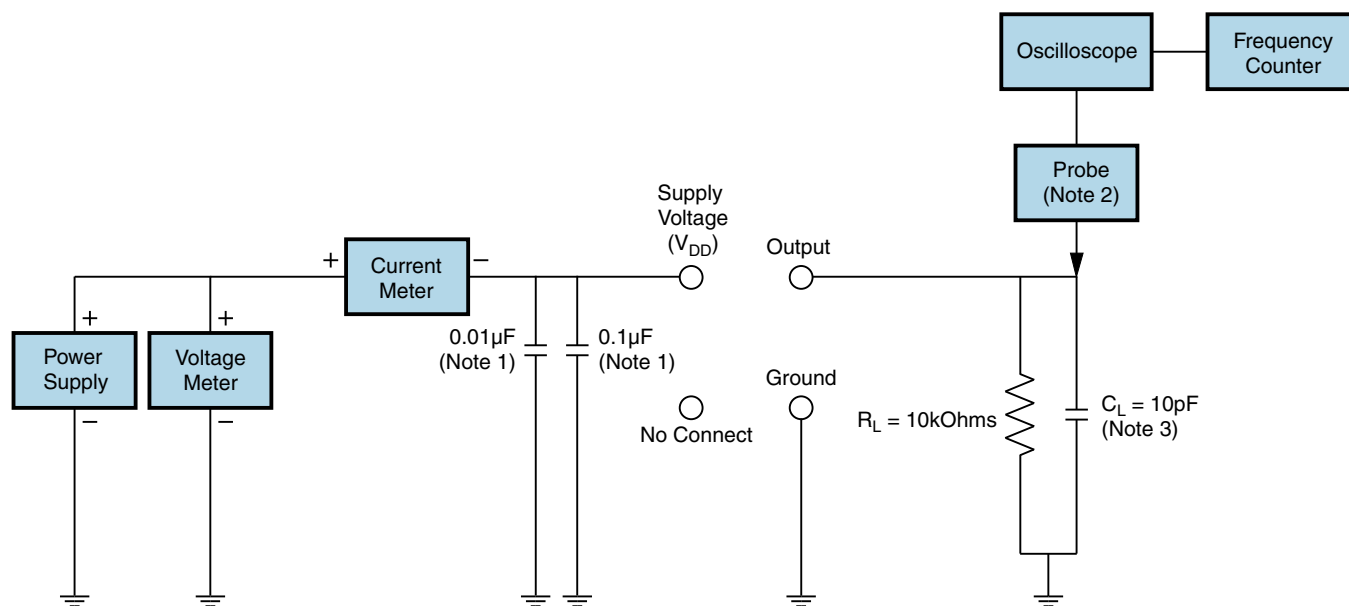
OUTPUT WAVEFORM



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Test Circuit for No Connect Option



Note 1: An external 0.01µF bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

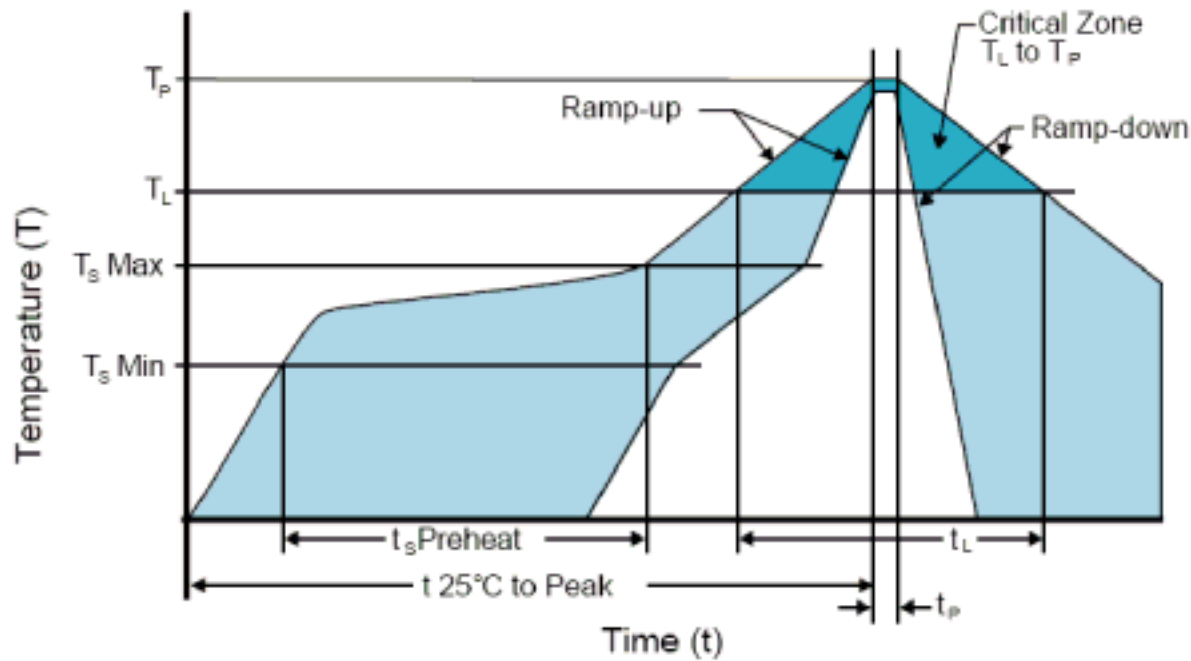
Note 2: A low input capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 220°C

TS MAX to TL (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (TS MIN)	N/A
- Temperature Typical (TS TYP)	150°C
- Temperature Maximum (TS MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
Ramp-up Rate (TL to TP)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum
Peak Temperature (TP)	220°C Maximum
Target Peak Temperature (TP Target)	220°C Maximum 1 Time / 215°C Maximum 1 Time
Time within 5°C of actual peak (tP)	15 Seconds Maximum 1 Time / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures listed are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures listed are applied to body of device.)